

N-Channel Super Junction Power MOSFET III

General Description

The series of devices use advanced trench gate super junction technology and design to provide excellent Rds(ON) with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

Features

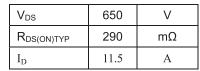
- New technology for high voltage device
- Low on-resistance and low conduction losses
- small package
- Ultra Low Gate Charge cause lower driving requirements
- 100% Avalanche Tested
- ROHS compliant

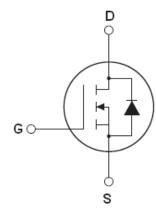
Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

Package Marking And Ordering Information

Device	Device Package	Marking
RM12N650HD	TO-263	12N650
RM12N650T2	TO-220	12N650
RM12N650TI	TO-220F	12N650





Schematic diagram







TO-263

TO-220

TO-220F

Table 1. Absolute Maximum Ratings ($T_c=25^{\circ}$ C)

Parameter	Symbol	RM12N650HD RM12N650T2	RM12N650TI	Unit
Drain-Source Voltage (V _{GS} =0V)	V _{DS}	65	50	V
Gate-Source Voltage (V _{DS} =0V), AC(f>1HZ)	V _G S	±30		V
Continuous Drain Current at T _C =25°C	I _{D (DC)}	11.5	11.5*	А
Continuous Drain Current at T _C =100°C	I _{D (DC)}	7	7*	А
Pulsed drain current (Note 1)	DM (pluse)	46	46*	А
Maximum Power Dissipation(T _C =25°C)	P_{D}	101	32.6	W
Derate above 25°C		0.81	0.26	w/°C
Single pulse avalanche energy (Note2)	Eas	144		mJ
Avalanche current ^(Note 1)	lanche current ^(Note 1) I _{AR} 6		5	А
Repetitive Avalanche energy , t_{AR} limited by T_{jmax} (Note 1)	E _{AR}	0.5		mJ

Parameter	Symbol	RM12N650HD RM12N650T2 RM12N650T	l Unit
Drain Source voltage slope, V _{DS} ≤480 V,	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS} \le 480 \text{ V}, I_{SD} < I_{D}$	dv/dt	15	V/ns
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55+150	°C

^{*} limited by maximum junction temperature

Table 2. Thermal Characteristic

Parameter	Symbol	RM12N650HD RM12N650T2	RM12N650TI	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R _{thJC}	1.24	3.83	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R _{thJA}	62	80	°C /W

 Table 3. Electrical Characteristics (TA=25℃ unless otherwise noted)

Table 3. Lieutiful Characteristics	ics (TA-23 Culless otherwise noted)					
Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	650			V
Zero Gate Voltage Drain Current(Tc=25℃)	I _{DSS}	V _{DS} =650V,V _{GS} =0V		0.05	1	μΑ
Zero Gate Voltage Drain Current(Tc=125℃)	I _{DSS}	V _{DS} =650V,V _{GS} =0V			100	μΑ
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250μA	3	3.5	4	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =7A		300	360	mΩ
Dynamic Characteristics	•		•		•	
Input Capacitance	C _{Iss}	\/ F0\/\\ 0\/		870		pF
Output Capacitance	C _{oss}	V_{DS} =50V, V_{GS} =0V, F=1.0MHz		54		pF
Reverse Transfer Capacitance	C _{rss}	F=1.UMHZ		1.8		pF
Total Gate Charge	Qg	\/ 400\/ 44.54		19		nC
Gate-Source Charge	Q _{gs}	V _{DS} =480V,I _D =11.5A,		6		nC
Gate-Drain Charge	Q_{gd}	V _{GS} =10V		6.5		nC
Switching times						
Turn-on Delay Time	t _{d(on)}			11		nS
Turn-on Rise Time	t _r	V _{DD} =380V,I _D =5.5A,		8		nS
Turn-Off Delay Time	t _{d(off)}	$R_G=3\Omega,V_{GS}=10V$		58	70	nS
Turn-Off Fall Time	t _f			9	14	nS
Source- Drain Diode Characteristics	•		•		•	
Source-drain current(Body Diode)	I _{SD}	T 05°0			11.5	Α
Pulsed Source-drain current(Body Diode)	I _{SDM}	T _C =25°C			46	Α
Forward on voltage	V _{SD}	Tj=25°C,I _{SD} =11.5A,V _{GS} =0V		0.9	1.2	V
Reverse Recovery Time	t _{rr}	T: 05°0 L 5 0A		220		nS
Reverse Recovery Charge	Q _{rr}	Tj=25°C,I _F =5.8A,		2.2		uC
Peak Reverse Recovery Current	I _{rrm}	di/dt=100A/µs		19		Α

Notes: 1.Repetitive Rating: Pulse width limited by maximum junction temperature



^{2.} Tj=25°C,VDD=50V,VG=10V, R_G=25 Ω

RATING AND CHARACTERISTICS CURVES (RM12N650HD/T2/TI)

Figure 1. Safe operating area

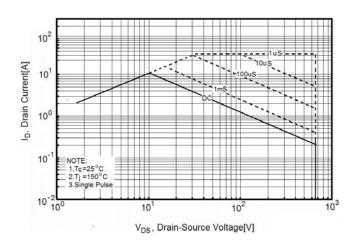


Figure 2. Safe operating area for TO-220F

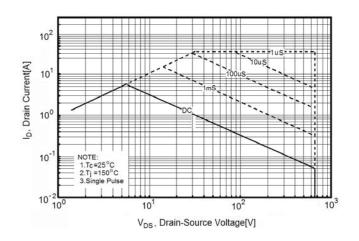


Figure 3. Source-Drain Diode Forward Voltage

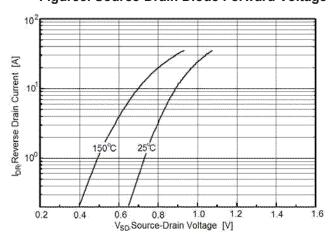


Figure 4. Output characteristics

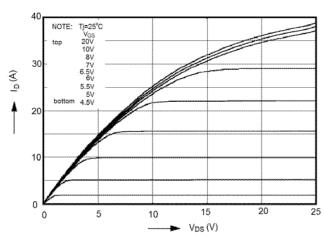


Figure 5. Transfer characteristics

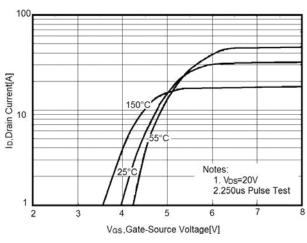
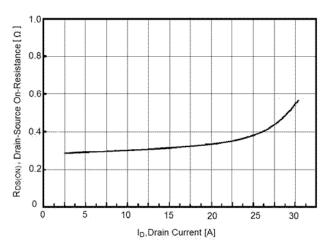


Figure 6. Static drain-source on resistance





RATING AND CHARACTERISTICS CURVES (RM12N650HD/T2/TI)

Figure 7. R_{DS(ON)} vs Junction Temperature

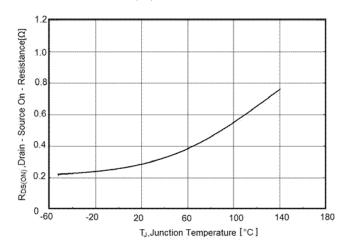


Figure 8. BV_{DSS} vs Junction Temperature

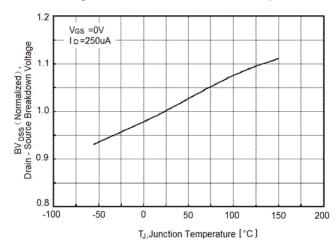


Figure 9. Maximum I_D vs Junction Temperature

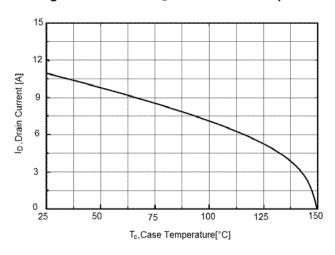


Figure 10. Gate charge waveforms

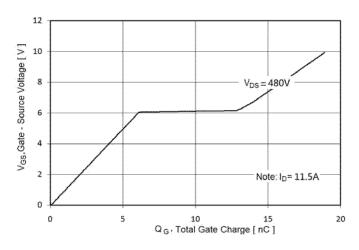


Figure11. Capacitance

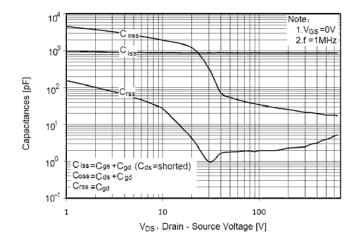
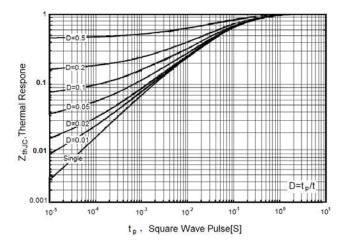


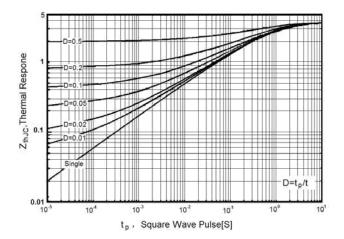
Figure 12. Transient Thermal Impedance





RATING AND CHARACTERISTICS CURVES (RM12N650HD/T2/TI)

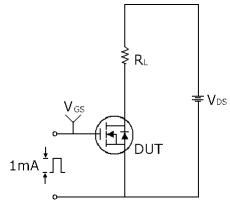
Figure 13. Transient Thermal Impedance for TO-220F

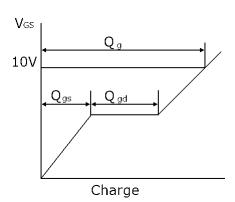




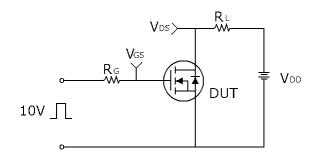
Test circuit

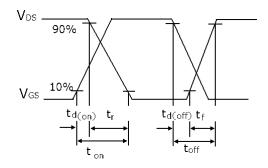
1) Gate charge test circuit & Waveform



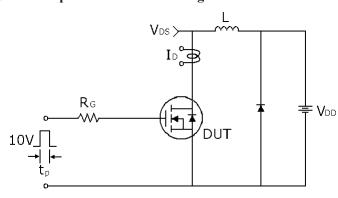


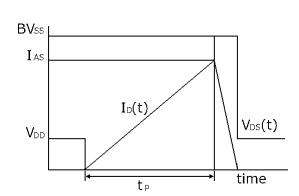
2) Switch Time Test Circuit:





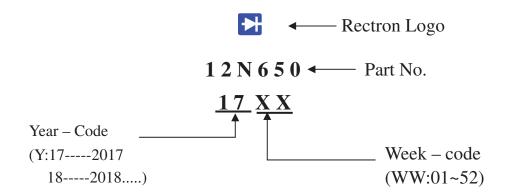
3) Unclamped Inductive Switching Test Circuit & Waveforms



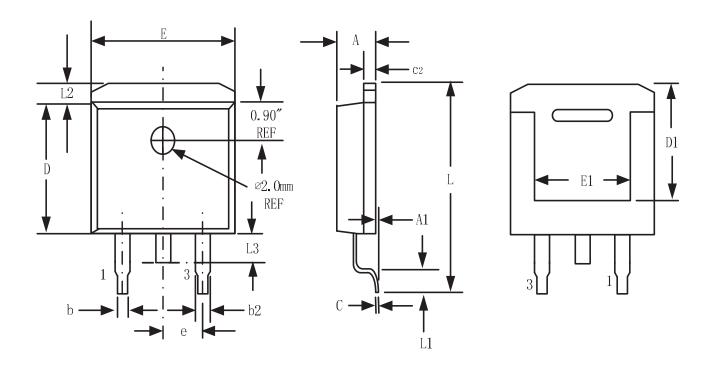




Marking on the body



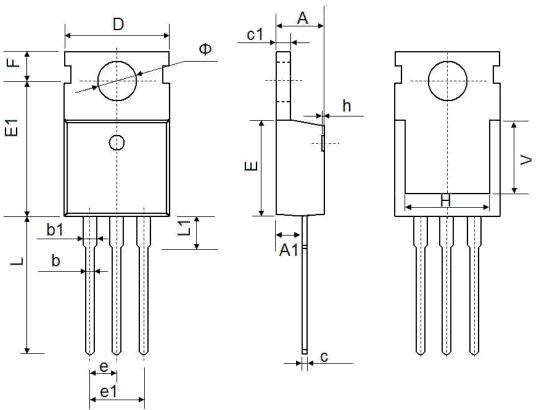
TO-263-3L Package Information



Symbol	Dimensions	Dimensions In Millimeters		In Inches
Symbol	Min.	Max.	Min.	Max.
А	4.32	4.57	0.170	0.180
A1	-	0.25		0.010
b	0.71	0.94	0.028	0.037
b2	1.15	1.40	0.045	0.055
С	0.46	0.61	0.018	0.024
c2	1.22	1.40	0.048	0.055
D	8.89	9.40	0.350	0.370
D1	8.01	8.23	0.315	0.324
Е	10.04	10.28	0.395	0.405
E1	7.88	8.08	0.310	0.318
е	2.54	BSC	0.100	BSC
L	14.73	15.75	0.580	0.620
L1	2.29	2.79	0.090	0.110
L2	1.15	1.39	0.045	0.055
L3	1.27	1.77	0.050	0.070



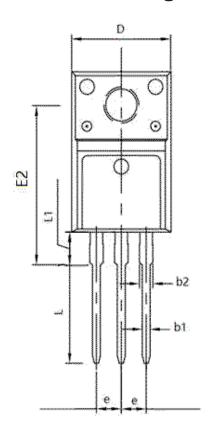
TO-220-3L-C Package Information

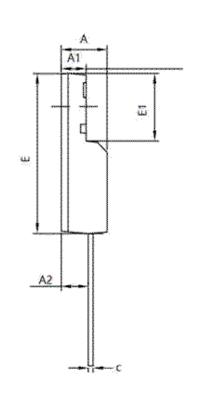


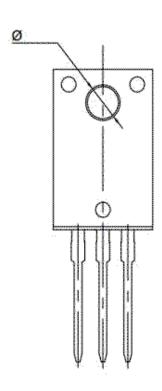
0	Dimensions In Millimeters		Dimension	s In Inches
Symbol	Min.	Max.	Min.	Max.
Α	4.400	4.600	0.173	0.181
A1	2.250	2.550	0.089	0.100
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
С	0.330	0.650	0.013	0.026
c1	1.200	1.400	0.047	0.055
D	9.910	10.250	0.390	0.404
E	8.9500	9.750	0.352	0.384
E1	12.650	12.950	0.498	0.510
е	2.540 TYP.		0.100 TYP.	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
Н	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.900	13.400	0.508	0.528
L1	2.850	3.250	0.112	0.128
V	7.500	REF.	0.295	REF.
Ф	3.400	3.800	0.134	0.150



TO-220F Package Information







Symbol	Dimensions In Millimeters		Dimension	s In Inches
	Min.	Max.	Min.	Max.
A	4.500	4.900	0.177	0.193
A1	2.340	2.740	0.092	0.108
A2	2.560	2.960	0.101	0.117
b1	0.700	0.900	0.028	0.035
b2	1.180	1.580	0.046	0.062
С	0.400	0.600	0.016	0.024
D	9.960	10.360	0.392	0.408
E	15.670	15.970	0.617	0.629
E1	6.500	6.900	0.256	0.272
E2	15.500	16.100	0.610	0.634
е	2.540	2.540 TYP) TYP
Ф	3.080	3.280	0.121	0.129
L	12.640	13.240	0.498	0.521
L1	3.030	3.430	0.119	0.135

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